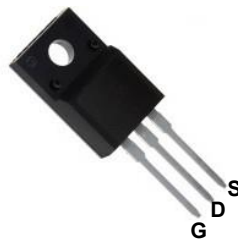
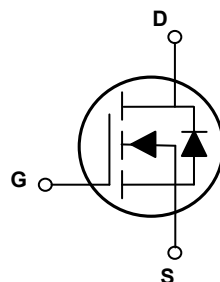


Main Product Characteristics

BV_{DSS}	900V
$R_{DS(ON)}$	340m Ω (Max)
I_D	12A



TO-220F



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFU90R340 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies, EV Charger, motor driver and a wide variety of other applications.

Absolute Maximum Ratings ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	900	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current, $T_C=25^{\circ}\text{C}^1$	I_D	12	A
Continuous Drain Current, $T_C=100^{\circ}\text{C}^1$		7.6	
Pulsed Drain Current, $T_C=25^{\circ}\text{C}^2$	$I_{D,pulse}$	36	A
Continuous Diode Forward Current, $T_C=25^{\circ}\text{C}^1$	I_S	12	A
Diode Pulsed Current, $T_C=25^{\circ}\text{C}^2$	$I_{S,pulse}$	36	A
Power Dissipation, $T_C=25^{\circ}\text{C}^3$	P_D	34	W
Single Pulsed Avalanche Energy ⁴	E_{AS}	360	mJ
MOSFET dv/dt Ruggedness, $V_{DS}=0$ to 480V	dv/dt	50	V/ns
Reverse Diode dv/dt, $V_{DS}=0$ to 480V, $I_{SD} \leq I_D$		15	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	3.67	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C/W}$
Operation and Storage Temperature Range	T_{stg}, T_J	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	900	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	2.9	-	3.9	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =900V, V _{GS} =0V	-	-	1	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V	-	-	±100	nA
Drain-Source On State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	0.28	0.34	Ω
		V _{GS} =10V, I _D =6A T _J =150°C	-	0.98	-	
Gate Resistance	R _G	F=1MHz, Open drain	-	16.6	-	Ω
Dynamic and Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =400V, I _D =10A V _{GS} =10V	-	53.8	-	nC
Gate-Source Charge	Q _{gs}		-	15.6	-	
Gate-Drain Charge	Q _{gd}		-	14.5	-	
Gate Plateau Voltage	V _{plateau}		-	5.3	-	V
Turn-On Delay Time	t _{d(on)}	V _{DS} =400V, R _G =2Ω V _{GS} =10V, I _D =10A	-	50	-	nS
Rise Time	t _r		-	32	-	
Turn-Off Delay Time	t _{d(off)}		-	121	-	
Fall Time	t _f		-	27.6	-	
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V F=100KHz	-	2786	-	pF
Output Capacitance	C _{oss}		-	94	-	
Reverse Transfer Capacitance	C _{rss}		-	3.9	-	
Effective Output Capacitance, Energy Related	C _{o(er)}	V _{GS} =0V, V _{DS} =0V-400V	-	58	-	
Effective Output Capacitance, Time Related	C _{o(tr)}		-	276	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =12A	-	-	1.3	V
Reverse Recovery Time	t _{rr}	V _R =400V I _S =10A, di/dt=100A/μs	-	300	-	nS
Reverse Recovery Charge	Q _{rr}		-	4.1	-	uC
Peak Reverse Recovery Current	I _{rrm}		-	25.3	-	A

Note:

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Pd is based on max. junction temperature, using junction-case thermal resistance.
4. V_{DD}=100V, V_{GS}=10V, L=75mH, starting T_J=25°C.

Typical Electrical and Thermal Characteristic Curves

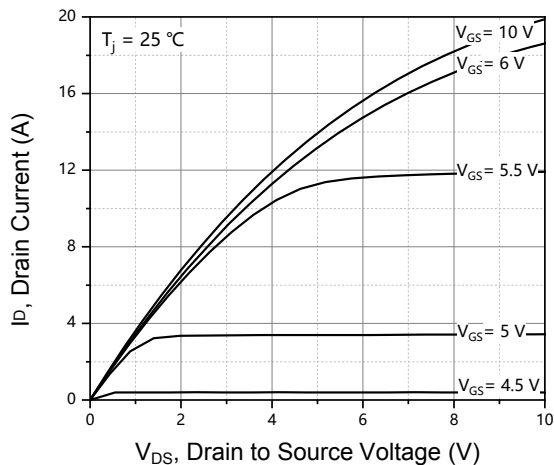


Figure 1. Typical Output Characteristics

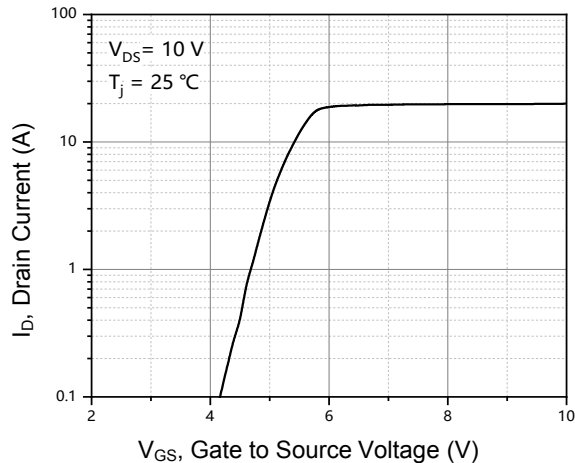


Figure 2. Typical Transfer Characteristics

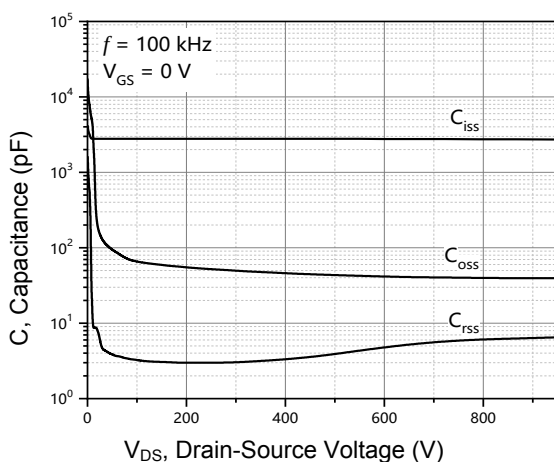


Figure 3. Typical Capacitances

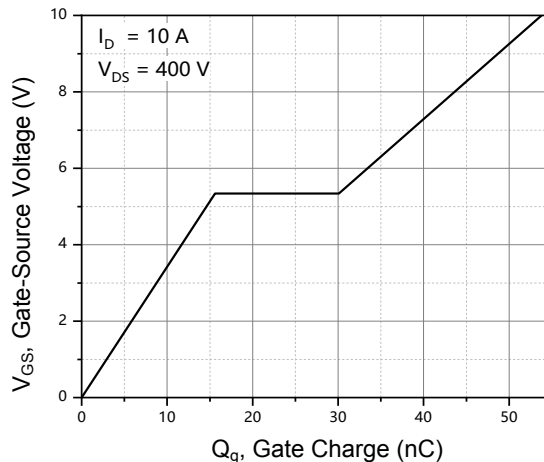


Figure 4. Typical Gate Charge

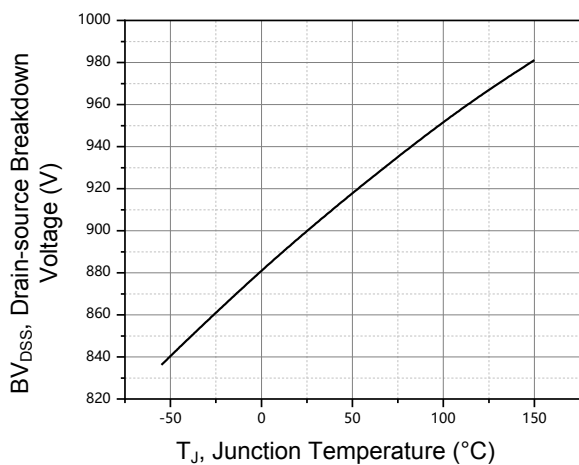


Figure 5. Drain-Source Breakdown Voltage

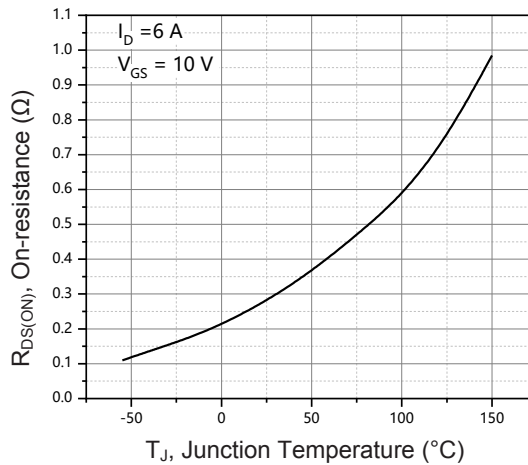


Figure 6. Drain-Source On-State Resistance

Typical Electrical and Thermal Characteristic Curves

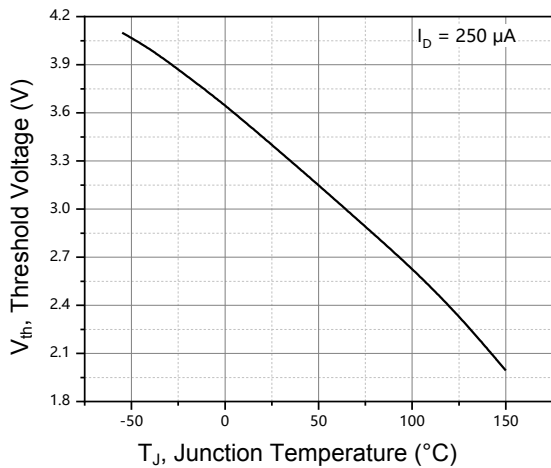


Figure 7. Threshold Voltage

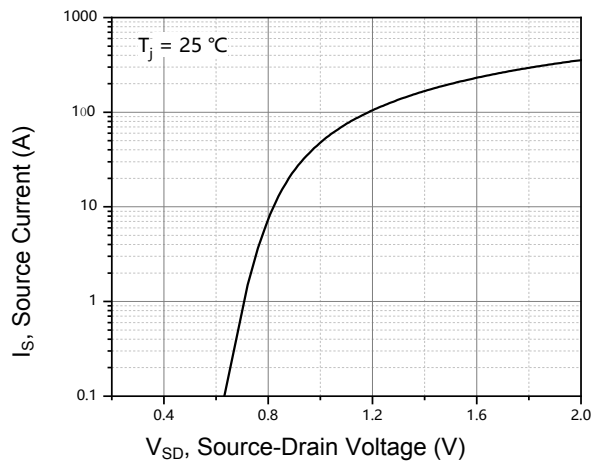


Figure 8. Forward Characteristic Of Body Diode

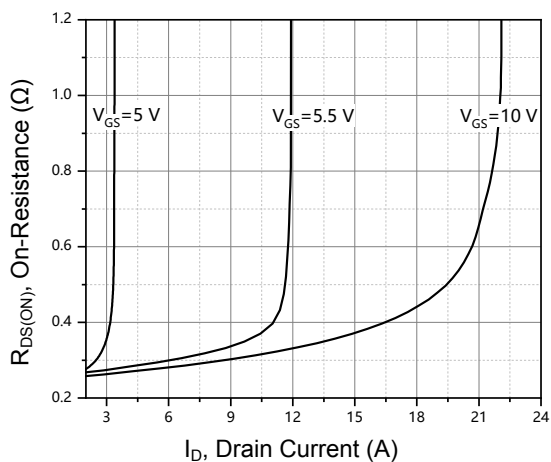


Figure 9. Drain-Source On-State Resistance

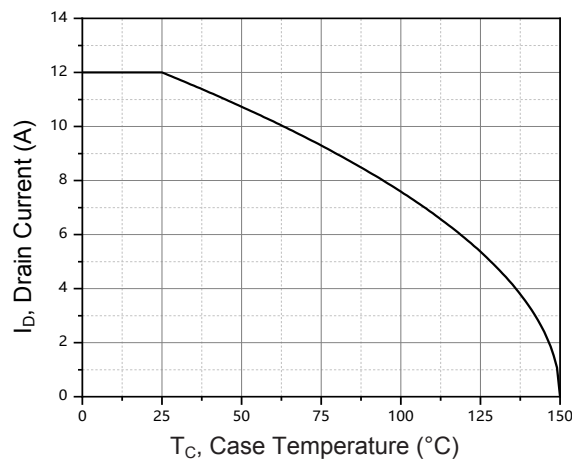


Figure 10. Drain Current

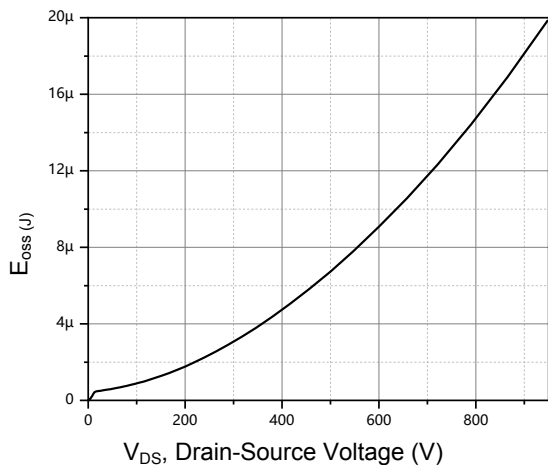


Figure 11. Typical Coss Stored Energy

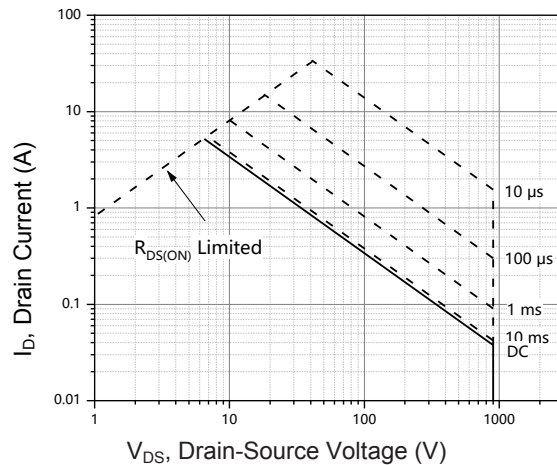


Figure 12. Safe Operation Area $T_c=25^{\circ}\text{C}$

Typical Electrical and Thermal Characteristic Curves

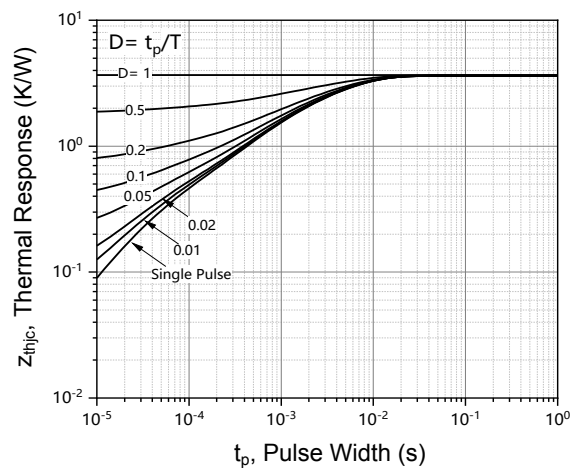
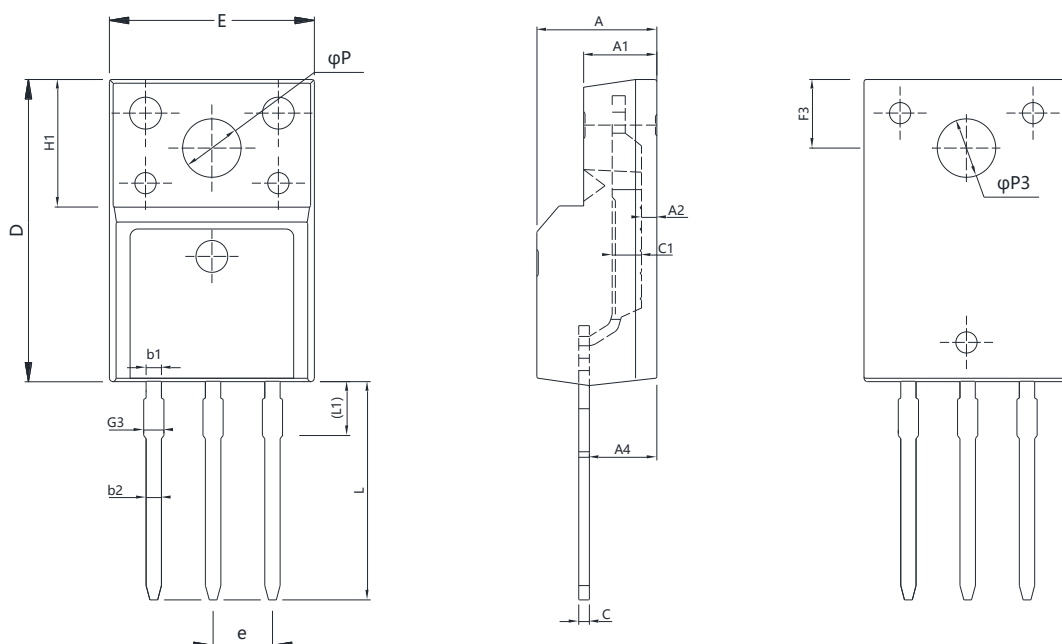


Figure 13. Max. Transient Thermal Impedance

Package Outline Dimensions (TO-220F)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
E	9.960	10.360	0.392	0.408
A	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	0.300	0.600	0.012	0.024
A4	2.560	2.960	0.101	0.117
c	0.400	0.650	0.016	0.026
C1	1.200	1.350	0.047	0.053
D	15.570	16.170	0.613	0.637
H1	6.700 REF		0.264 REF	
e	2.540 BSC		0.100 BSC	
L	12.680	13.280	0.499	0.523
L1	2.880	3.180	0.113	0.125
φP	3.030	3.380	0.119	0.133
φP3	3.150	3.650	0.124	0.144
F3	3.150	3.450	0.124	0.136
G3	1.250	1.550	0.049	0.061
b1	1.180	1.430	0.046	0.056
b2	0.700	0.950	0.028	0.037